

in Silicone resin

Solvent based coatings

Evonik Tego formulation No. 402

Rev. Number: 01.01

08/07

Function	Product	Producer	PBW
Methyl phenyl silicone resin	SILIKOPHEN® P80/MPA	Evonik	34.40
Copper chromite black spinel	HEUCODUR® Black 9-100	Sudarshan	8.00
Carbon black pigment	PRINTEX® L	Orion Engineered Carbons	2.00
Mica/quartz/chlorite filler	Plastorit® 0000	Imerys	6.00
Anticorrosive pigment	HEUCOPHOS® ZPO	Sudarshan	6.00
Grind.			
Solvent	Butyl acetate		1.50
Solvent	Isopropyl alcohol		0.05
Wetting and dispersing agent	TEGO® Dispers 700	Evonik	0.15
Rheology modifier	BENTONE® 38	Elementis	0.30
Mix until uniform paste prior to addition.			
Solvent	Methoxypropyl acetate		30.60
Solvent	Butyl acetate		11.00
Add while stirring.			

100.00

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